

ABSTRACT OF THE DISCLOSURE

An insulating sheet which connects a semiconductor chip and a wiring substrate is provided between the semiconductor chip and the wiring substrate. The insulating sheet has windows therethrough at positions corresponding to those of connection pads of the wiring substrate and has leads, one end of each of the leads being fixed on the sheet and the other end of each of the leads protruding from the opposite surface of the sheet through a window. Each of solder balls of the semiconductor chip is connected to the fixed one end of one of the leads, and each of the connection pads is connected to the other end of each of the leads to electrically connect the semiconductor chip and the wiring substrate.